Dear Customer,

This is to formally inform you that ams AG received a “Product Discontinuation Notice” from our supplier, Fujifilm Electronic Materials, that is directly affecting the fab B product(s) that we are delivering to you. The supply of currently used type of Polyimid Wafer Coating (DURIMIDE 9005) will be discontinued and replaced by another type (FB5610-12) which is proposed as equivalent replacement coating material from Fujifilm Electronic Materials.

In order to reasonably protect the supply of your product, ams AG is currently qualifying this replacement coating material.

The following product(s) will be affected:

<table>
<thead>
<tr>
<th>product</th>
<th>product description</th>
<th>material ID</th>
</tr>
</thead>
<tbody>
<tr>
<td>AS5900</td>
<td>AS5900-ZFBT FBGA248 LF T&amp;RDP</td>
<td>502880005</td>
</tr>
</tbody>
</table>

Note: this only affects wafer material produced in our Fab B. TSMC wafers are not affected.
Timing of change:

ams AG qualification is ongoing and will be finished in Q2 / 2019. Samples with new coating material will be available from May 2019. Material with new polyimid coating will be delivered from Q4 / 2019 onwards.

Set of qualification tests:

ams AG is qualifying the new coating material based on AEC-Q100 standards. Detailed results of the qualification will be available upon request.

If you do have further questions please do not hesitate to contact us.

Please be advised that unless we receive your written refusal concerning this PCN within 30 days, the PCN shall be deemed accepted.

Best regards,

Herwig Klimesch
ams AG
Vice President Quality